



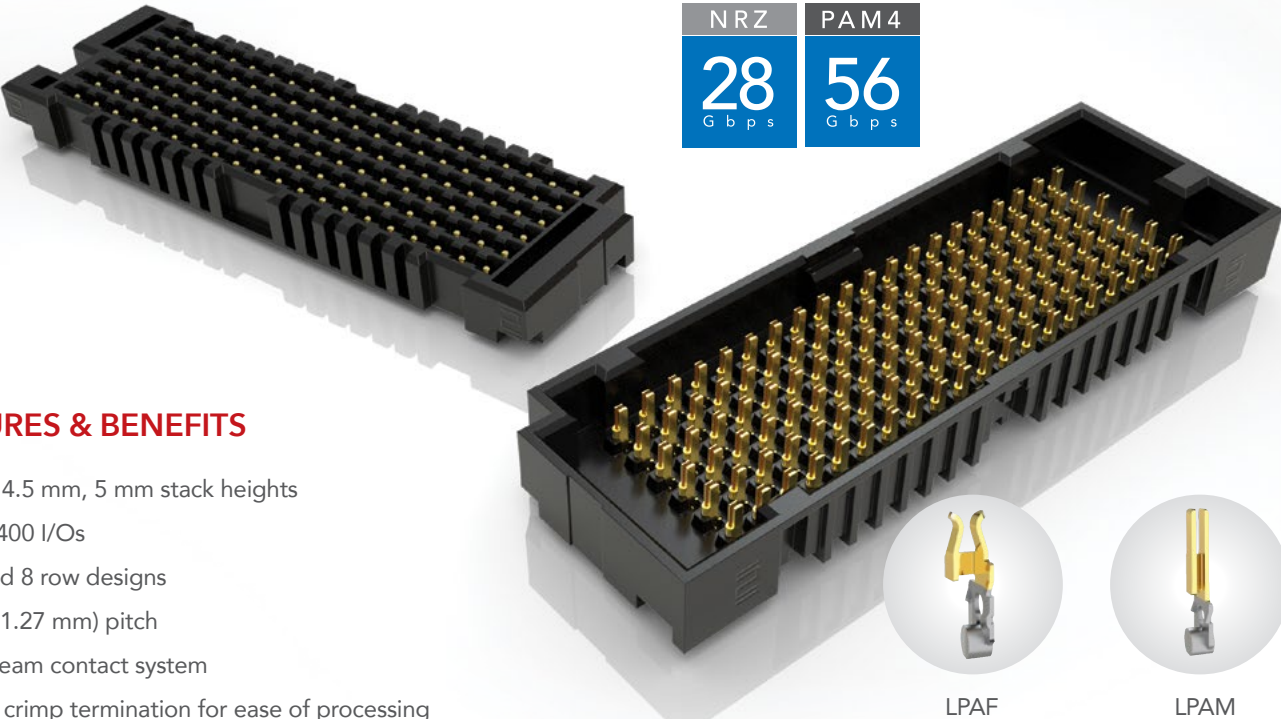
**THE DATASHEET OF
LPAF-30-03.0-L-06-2-K-TR**



LPARRAY™

LOW PROFILE OPEN-PIN-FIELD ARRAYS


(1.27 mm) .050" PITCH




| | |
|------|------|
| NRZ | PAM4 |
| 28 | 56 |
| Gbps | Gbps |

FEATURES & BENEFITS

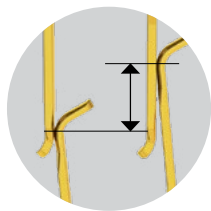
- 4 mm, 4.5 mm, 5 mm stack heights
- Up to 400 I/Os
- 4, 6 and 8 row designs
- .050" (1.27 mm) pitch
- Dual beam contact system
- Solder crimp termination for ease of processing
- Board stacking standoffs available to assist with unmating and reduce risk for component damage on board



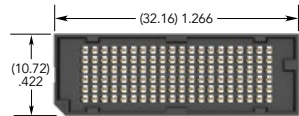
LPAF
Dual Beam Contact



LPAM
Dual Blade Terminal

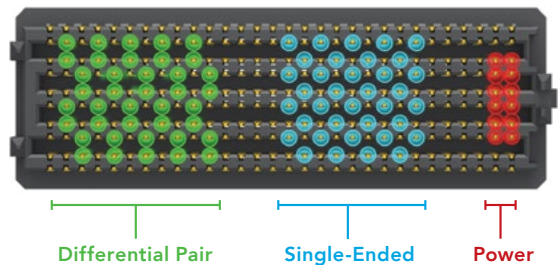


(0.51 mm) .020"
Nominal Wipe



LPAM Series; 120 pins

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS (LPAM/LPAF)

| PITCH | TOTAL PINS | INSULATOR MATERIAL | CONTACT MATERIAL | PLATING | CURRENT RATING | WORKING VOLTAGE | LEAD-FREE SOLDERABLE |
|-------------------|----------------|--------------------|------------------|----------------------------------|---|-----------------|----------------------|
| 1.27 mm x 1.27 mm | Up to 400 I/Os | Black LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | 2.2 A per pin (8 adjacent pins powered) | 250 VAC | YES |

(1.27 mm) .050" PITCH • LOW PROFILE OPEN-PIN-FIELD ARRAYS

| SERIES | NO. PINS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | K | "X"R |
|------------------|------------------------|--|--|-------------------|---|---|--|
| LPAM Terminal | -10, -20, -30, -40, | -01.0 = (1.0 mm) .039" (LPAM only) | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail | -04 -06 -08 | -1 = Tin/Lead Alloy Solder Crimp | | -K = Polyimide film Pick & Place Pad |
| LPAF Socket | -50 (-08 rows only) | -01.5 = (1.5 mm) .060" (LPAM only) | -S = 30 μ" (0.76 μm) Gold on contact area, Matt Tin on solder tail | | -2 = Lead-Free Solder Crimp | | -TR =Tape & Reel |
| | | -03.0 = (3.0 mm) .118" (LPAF only) | | | | | -FR =Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) |
| | | -03.5 = (3.5 mm) .138" (LPAF only) | | | | | |

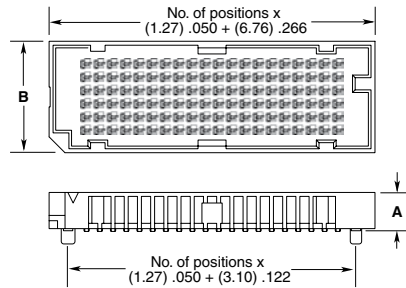
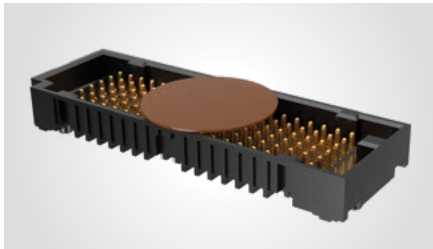
LPAM

Board Mates:

LPAF

Standoffs:

JSO, SO



| NO. OF ROWS | B |
|-------------|--------------|
| -04 | (8.18) .322 |
| -06 | (10.72) .422 |
| -08 | (13.26) .522 |

| LEAD STYLE | A |
|------------|-------------|
| -01.0 | (3.68) .145 |
| -01.5 | (4.19) .165 |

View complete specifications at: samtec.com?LPAM

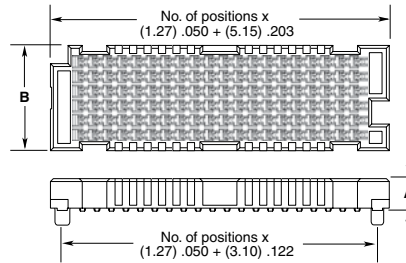
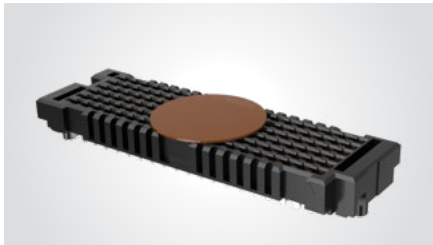
LPAF

Board Mates:

LPAM

Standoffs:

JSO, SO



| NO. OF ROWS | B |
|-------------|--------------|
| -04 | (6.71) .264 |
| -06 | (9.25) .364 |
| -08 | (11.79) .464 |

| LEAD STYLE | A |
|------------|-------------|
| -03.0 | (2.79) .110 |
| -03.5 | (3.30) .130 |

MATED HEIGHTS*

| LPAM LEAD STYLE | LPAF LEAD STYLE | |
|-----------------|-----------------|-------------|
| | -03.0 | -03.5 |
| -01.0 | (4.00) .157 | (4.50) .177 |
| -01.5 | (4.50) .177 | (5.00) .197 |

*Processing conditions will affect mated height.



Notes:

Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?LPAF

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View LPAF-30-03.0-L-06-2-K-TR on WIN SOURCE](#)
-  [Samtec Inc. Information](#)

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-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management